

5-2-06

Substitute for form 1465A/PTO  
**INFORMATION DISCLOSURE  
 STATEMENT BY APPLICANT**  
 (Use as many sheets as necessary)

PTO/GR/084R1D-01  
 Approved for use through 10/31/2002 GPO:051-000  
 U.S. Patent & Trademark Office U.S. DEPARTMENT OF COMMERCE

Complete if Known	
<b>Application Number</b>	10/808,192
<b>Filing Date</b>	March 24, 2004
<b>First Named Inventor</b>	Suh, Daewoong
<b>Group Art Unit</b>	2841
<b>Examiner Name</b>	Vigushin, John
Sheet 1 of 1	Attorney Docket No: 884.C25US1

### US PATENT DOCUMENTS

Examiner Initials*	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date if Appropriate

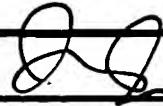
### FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	T <sup>2</sup>

### OTHER DOCUMENTS – NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No <sup>1</sup>	Include name of the author (In CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
		ROMAN, JOHN W., et al., "Low Stress Die Attach by Low Temperature Transient Liquid Phase Bonding", <u>The International Society for Hybrid Microelectronics (ISHM) Symposium Proceedings, October 1992, (October 1992), 1-6</u>	

EXAMINER



DATE CONSIDERED

11/12/06

Substitute Disclosure Statement Form (PTO-1465)

\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 608. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. <sup>1</sup> Applicant's unique citation designation number (optional) <sup>2</sup> Applicant is to place a check mark here if English language Translation is attached